

Amendments to the Specification:

Please replace the paragraph beginning at page 3, line 8 with the following amended paragraph:

Fig. 2 shows an a laminate for encapsulating an electrical device in accordance with one embodiment of the invention; and

Figs. 3-5 illustrate a process for encapsulating an electrical device, ; and

Please replace the paragraph beginning at page 5, line 8 with the following amended paragraph:

The OLED pixels are materials formed on a substrate 105. In one embodiment, the substrate comprises a transparent substrate and serves as the display surface. The substrate is prepared to support a laminate 120. For example, supports 150 130 are provided surrounding the OLEDs to support the laminate. The laminate covers the device and hermetically seals the components, protecting them from the environment. The device can also include support posts (not shown in FIG. 6) in the non-active regions to provide support for the laminate. This prevents the laminate from collapsing onto the components and affecting the device's functionality. Support posts are particularly useful for flexible devices. Providing support posts in non-active regions of the device is described in concurrently filed International Patent Application titled "Encapsulation of a Device", PCT International Publication Number WO 01/04963 A1, published January 18, 2001, which is herein incorporated by reference.

Please add the following new paragraph after the paragraph ending at page 3, line 12:

Fig. 6 shows an embodiment that includes support posts.

Please add the following new paragraph after the paragraph ending at page 6, line 2:

One embodiment of a device with support posts is shown in FIG. 6. Active components 610 include organic LED pixels. An organic LED pixel comprises at least one organic layer 614

between first and second electrodes 612 and 616. The active components 610 are located on active regions 615 of the substrate 601 and are separated by non-active regions 620. Support posts 630 are located in the non-active regions 620 of the substrate 601 and in the periphery of the device surrounding the active regions 615. The support posts 630 can be provided in one, some, or in all the non-active regions 620. A cap 120, which in this embodiment is a laminate, is mounted on the support posts 630 to encapsulate the device in order to protect the active components from air and/or moisture. The height of the support posts 630 creates a gap or cavity 618 between the surface of the LED pixels and cap 120. The gap should be sufficient to prevent the cap from contacting the LED pixels. Typically, the gap is about 1-10 microns in height. Of course, the gap height can vary due to the amount of stress induced (e.g., amount of bending required from the device, thickness of the cover layer, and lateral distance between support posts).

Applicant : Ewald Guenther et al.
Serial No. : 09/786,833
Filed : March 9, 2001
Page : 14 of 17

Attorney's Docket No.: 12406-012001 / 1999P8115 US
E/GS

Amendments to the Drawings:

The attached drawing sheet includes new Fig. 6.